

Organizers

VDE/VDI-Society Microelectronics, Microsystems- and Precision Engineering (GMM)

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In cooperation with:

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Venue: Hilton Hotel in Dresden



Dresden at
the river Elbe

The EMLC 2013 International Program Committee

Conference Chair	Uwe Behringer, UBC Microelectronics, Ammerbuch, Germany
Co-Conference Chair	Naoya Hayashi, DNP, Saitama, Japan Chris Gale, Applied Materials, Dresden, Germany
Program Chair	Wilhelm Maurer, Infineon, Munich, Germany
Co-Program Chairs	Rolf Seltmann, Globalfoundries, Dresden, Germany Jo Finders, ASML, Veldhoven, Netherlands

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Parkson Chen, Taiwan Mask Corp., Hsinchu, Taiwan
Brid Connolly, Toppan Photomasks GmbH, Dresden, Germany
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Barbara Lauche, Photonics MZD GmbH, Dresden, Germany
Hans Löschner, IMS Nanofabrication AG, Vienna, Austria
Chris Progler, Photonics Inc., USA
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Carmelo Romeo, Numonyx, Agrate Brianza, Italy
Hella Scheer, University of Wuppertal, Germany
Thomas Scherübl, Carl Zeiss SMS GmbH, Jena, Germany
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Mark Staples, Globalfoundries, Dresden, Germany
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Jacques Waelpoel, ASML, Veldhoven, Netherlands
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Hermann Wolf, Photonics MZD GmbH, Dresden, Germany
Stefan Wurm, SEMATECH, Albany, NY, USA
Larry Zurbrick, Agilent Technologies, Santa Clara, CA, USA

Please find the members of the **International Steering Committee** of the EMLC on the website: www.emlc2013.com

Cover picture: Courtesy of Toppan Photomasks

GMM

VDE/VDI-GESELLSCHAFT
MIKROELEKTRONIK, MIKROSYSTEM-
UND FEINWERKTECHNIK



Call for Papers

The 29th European Mask and Lithography Conference EMLC 2013

June 25 – 27, 2013

Hilton Hotel

Dresden, Germany

www.EMLC2013.com



The VDE/VDI-Society Microelectronics, Microsystems and Precision Engineering (GMM) and UBC Microelectronics in cooperation with BACUS, PMJ, SEMI-Europe, and SPIE, are pleased to announce the

29th European Mask and Lithography Conference, EMLC 2013

at the Hilton Hotel in Dresden, Germany
June 25 - June 27, 2013

The focus of this 2 ½ -day conference is state-of-the-art of mask technology and lithography, such as mask manufacturing, mask business, lithography and mask applications, emerging mask & lithography technologies, and mask & lithography equipment.

This conference has annually brought together scientists, researchers, engineers and developers from around the world to present papers at the forefront of research, manufacturing and application. It provides a place where mask makers, mask users, and their tool suppliers become acquainted with new developments and results.

Conference Schedule

The conference will start on Tuesday, June 25, 2013 at 01:00 PM with a Keynote Session. The conference will close on Thursday, June 27, 2013, late afternoon. The Poster Session will be held on Wednesday evening followed by the Conference Banquet Dinner.

Technical Exhibition

From Tuesday noon to Thursday noon, (June 25th to June 27th 2013) there will be a technical exhibition with booth space for about 30 exhibitors. Presentation tables and pin boards will be available. To be part of this Technical Exhibition, please return the **enclosed registration form** to the conference chairperson as soon as possible, since exhibition space is limited.

Conference Chairperson and Exhibition Organization

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Abstract Information

Abstract quality will be the basis for selection of conference presentations. The abstracts will be assessed for:

- Originality of work
- Specific results reported
- Potential impact and interest to the attendees.

Therefore, we highly recommend that your abstract contains enough detail to clearly describe the content of your presentation. We recommend an abstract length of two pages (including figures, diagrams, formatted text) as Word and PDF.

Commercial papers, papers with no new research / development content, and papers where significant information is missing will not be accepted.

All accepted abstracts will be printed, bound and handed out to the participants of the conference.

In order to submit your abstract, please open the web site

www.EMLC2013.com

There you will find a link to myspie.org

■ Deadline for Abstracts: camera ready April 19th 2013

➤ By submitting an abstract you agree to

- Present your work in person at the conference and
- Submit a manuscript in time

Authors will be notified of the acceptance of their submissions by **May 03rd 2013**; further manuscript format and layout instructions will be provided at that time.

Manuscripts:

Please submit the original of the manuscript as early as possible but not later than the

■ Deadline for Manuscripts: camera ready June 14th 2013

Further information on the submission procedure can be found at **www.emlc2013.com**.

All manuscripts will be subjected to a critical peer review before they are accepted for publication.

Please note that late submissions may not be published.

Manuscripts will be published by SPIE, also on the SPIE Digital Library, so please follow the instructions provided at **<http://spie.org/x14101.xml>**

Conference Topics

Presentations are solicited for the following and related topics:

Mask Manufacturing

- Mask Data Preparation
- Pattern Generation: Writing, Etch, etc.
- Photomask Processes & Materials
- Metrology Tools & Technologies
- Defect Inspection & Repair
- Cleaning & Haze
- Pellicles & Mask Boxes
- Mask Process Yield & Cycle Time
- Photomasks for RET & OPC; PSM
- Masks for NGL: E-Beam, EUV, NIL, etc.

Mask Business

- Mask Business and Management
- Mask Cost and Mask Development Strategy
- Future Mask Demand

Lithography and Mask Application

- Double Patterning
- RET, OPC, PSM, MEEF
- Resist
- Mask Defect Printability
- Optical Materials
- Immersion Lithography
- Immersion Defectivity
- Alternate Immersion Fluids
- Lithography Process Control
- Lithography Simulation

Emerging Mask and Lithography Technologies

- EUV Materials, Tools & Processes
- EUV Mask Infrastructure
- NIL
- Direct Write / Maskless Technologies

Mask and Lithography Equipment

- Mask Manufacturing

NEW !!!

Semiconductors applied in Automotive

NEW !!!

Semiconductors in MEMS Applications

NEW !!!

Patterned Media